BOARD TITLE: PAINEL_MEB REVISIONS DESCRIPTION: AUTHOR: CCB 1 00 - Initial revision - Jun/4/2016 1 01 - Rtcc + mac address chip, with cr2032 battery - Nov/16/2016 CODE NUMBER: REVISION: 1 01 LAYER STACKUP: TOP & BOTTOM: SIGNAL + GND PLANE GENERAL NOTES: 1. LAMINATE SPECIFICATIONS: 4. SILKSCREEN MASK: - TOTAL THICKNESS: 1.6 mm +/- 0.2 mm - WHITE (THERMAL CURE EPOXY) - LAYER NUMBERS: 2 5. SOLDER MASK: - Cu THICKNESS (FINISHED): 1 oz / 1 oz - BOTH SIDES - RAW MATERIAL: FR-4 - GREEN EPOXY THERMAL CURE OR PHOTO IMAGEABLE - TG MIN .: 150 °C - IONIC CONTAMINATION AFTER SOLDERING: 14 ug NaCl / in2 MAX. - TD MIN : 310 °C - COVER VIAS WITH SOLDER MASK ON BOTH SIDES 2. HOLE CHARACTERISTICS: 6. SPECIFIED STANDARDS: - PLATED HOLE TOLERANCE: +/- 0.1 mm - IPC-6011 CLASS 2 / IPC-6012 CLASS 2 / IPC-A-600 CLASS 2 - NON PLATED HOLE TOLERANCE: +/- 0.1 mm 7 ADDITIONAL NOTES: - DISPLACEMENT: 0.1 mm MAX - DIMENSIONAL TOLERANCE: +/- 0.2 mm - Cu THICKNESS ON HOLE: 20 um + SnPb MIN. - ELECTRICAL TESTS ARE MANDATORY 3. FINISHING: - GERBER MODIFICATIONS ARE ONLY ALLOWED - HOT AIR SOLDER LEVELING (HASL) - SnPb WITH EXPLICIT AUTHOR / RESPONSIBLE AUTHORIZATION MAUÁ PAINEL_MEB - 1_01 - 2016/NOV IMT - INSTITUTO MAUÁ DE TECNOLOGIA FDI NSEE ă

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